DGG, DGV, OR DL PACKAGE

(TOP VIEW)

SCES095D-MARCH 1997-REVISED SEPTEMBER 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Checks Parity
- Able to Cascade With a Second SN74ALVCH16903
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

DESCRIPTION

This 12-bit universal bus driver is designed for 2.3-V to 3.6-V V_{CC} operation.

The SN74ALVCH16903 has dual outputs and can operate as a buffer or an edge-triggered register. In both modes, parity is checked on APAR, which arrives one cycle after the data to which it applies. The YERR output, which is produced one cycle after APAR, is open drain.

MODE selects one of the two data paths. When MODE is low, the device operates as an edge-triggered register. On the positive transition of the clock (CLK) input and when the clock-enable

56**∏** CLK OE [1Y1 🛮 2 55**∏** 1A 1Y2 **∏**3 54 11A/YERREN GND 4 53 GND 52 11Y1 2Y1 2Y2 **[**]6 51 1 11Y2 50 V_{CC} V_{CC} L 3Y1 **[**]8 49**∏** 2A 3Y2 **[**]9 48 3A 4Y1 110 47 **1** 4A 46∏ GND GND LI11 4Y2 112 45 12A 5Y1 **∏**13 44**∏** 12Y1 43 12Y2 5Y2 114 6Y1 []15 42 1 5A 6Y2 116 41 6A 7Y1 17 40 7A 39 T GND GND 118 7Y2 []19 38 APAR 8Y1 [**1**20 37**∏** 8A 8Y2 **1**21 36 YERR V_{CC} **□**22 35 V_{CC} 9Y1 **[**]23 34 🛮 9A 33 MODE 9Y2 **∐**24 GND 25 32 GND 10Y1 **1**26 31 T 10A 10Y2 **1**27 30 PARI/O PAROE 28 29 CLKEN

(CLKEN) input is low, data set up at the A inputs is stored in the internal registers. On the positive transition of CLK and when CLKEN is high, only data set up at the 9A–12A inputs is stored in their internal registers. When MODE is high, the device operates as a buffer and data at the A inputs passes directly to the outputs. 11A/YERREN serves a dual purpose; it acts as a normal data bit and also enables YERR data to be clocked into the YERR output register.

When used as a single device, parity output enable (PAROE) must be tied high; when parity input/output (PARI/O) is low, even parity is selected and when PARI/O is high, odd parity is selected. When used in pairs and PAROE is low, the parity sum is output on PARI/O for cascading to the second SN74ALVCH16903. When used in pairs and PAROE is high, PARI/O accepts a partial parity sum from the first SN74ALVCH16903.

A buffered output-enable (\overline{OE}) input can be used to place the 24 outputs and \overline{YERR} in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

 $\overline{\text{OE}}$ does not affect the internal operation of the device. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

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DESCRIPTION (CONTINUED)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16903 is characterized for operation from 0°C to 70°C.

FUNCTION TABLES

FUNCTION

		INPUTS			OUT	PUTS
ŌĒ	MODE	CLKEN	CLK	Α	1Yn ⁽¹⁾ –8Yn ⁽¹⁾	9Yn ⁽¹⁾ –12Yn ⁽¹⁾
L	L	L	↑	Н	Н	Н
L	L	L	\uparrow	L	L	L
L	L	Н	\uparrow	Н	Y_0	Н
L	L	Н	\uparrow	L	Y_0	L
L	Н	Χ	Χ	Н	Н	Н
L	Н	Χ	Χ	L	L	L
Н	Χ	X	Χ	Χ	Z	Z

(1) n = 1 or 2

PARITY FUNCTION

		INF	PUTS			OUTPUT
ŌĒ	PAROE (1)	11A/YERREN ⁽²⁾	PARI/O	Σ OF INPUTS 1A-10A = H	APAR	YERR
L	Н	L	L	0, 2, 4, 6, 8, 10	L	Н
L	Н	L	L	1, 3, 5, 7, 9	L	L
L	Н	L	L	0, 2, 4, 6, 8, 10	Н	L
L	Н	L	L	1, 3, 5, 7, 9	Н	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	L	L
L	Н	L	Н	1, 3, 5, 7, 9	L	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	Н	Н
L	Н	L	Н	1, 3, 5, 7, 9	Н	L
Н	Х	X	Х	X	Х	Н
L	Х	Н	Х	Х	Х	Н

- (1) When used as a single device, PAROE must be tied high.
- (2) Valid after appropriate number of clock pulses have set internal register

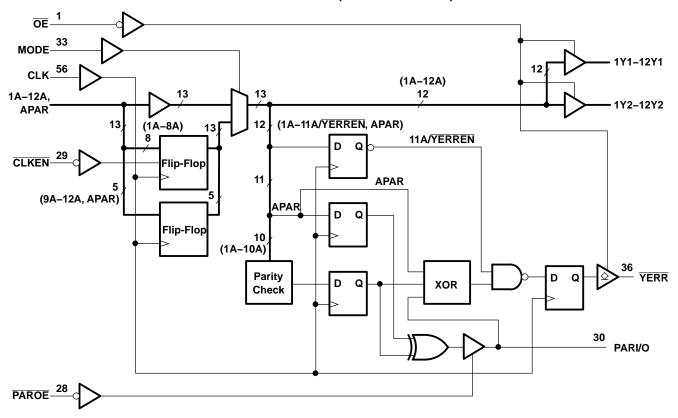
PARI/O FUNCTION(1)

	INPUTS		OUTPUT
PAROE	Σ OF INPUTS 1A-10A = H	APAR	PARI/O
L	0, 2, 4, 6, 8, 10	L	L
L	1, 3, 5, 7, 9	L	Н
L	0, 2, 4, 6, 8, 10	Н	Н
L	1, 3, 5, 7, 9	Н	L
Н	Χ	X	Z

 This table applies to the first device of a cascaded pair of SN74ALVCH16903 devices.



LOGIC DIAGRAM (POSITIVE LOGIC)







ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_{I}	Input voltage range ⁽²⁾	· · ·			V
Vo	Output voltage range ⁽²⁾⁽³⁾	utput voltage range ⁽²⁾⁽³⁾			
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GNI)		±100	mA
		DGG package		81	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGV package		86	°C/W
		DL package		74	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

				MIN	MAX	UNIT
V _{CC}	Supply voltage			2.3	3.6	V
V	Lligh lovel input veltage	V _{CC} = 2.3 V to 2.7 V		1.7		V
V_{IH}	High-level input voltage	V _{CC} = 2.7 V to 3.6 V		2		V
V	Low lovel input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$			0.7	V
V_{IL}	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$			0.8	V
VI	Input voltage			0	V _{CC}	V
Vo	Output voltage			0	V _{CC}	V
		V _{CC} = 2.3 V	Y port		-12	
	High-level output current	$V_{CC} = 2.7 \text{ V}$	r port		-12	mA
I _{OH}	r ligh-level output current	V _{CC} = 3 V	PARI/O		-12	ША
		v _{CC} = 3 v	Y port		-24	
		V _{CC} = 2.3 V	Y port		12	
		$V_{CC} = 2.7 \text{ V}$	r port		12	
I_{OL}	Low-level output current		PARI/O		12	mA
		$V_{CC} = 3 V$	Y port		24	
			YERR output		24	
Δt/Δν	Input transition rise or fall rate)		0	10	ns/V
T _A	Operating free-air temperatur	е		0	70	°C

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

i	PARAMETER	TEST C	CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT
		I _{OH} = -100 μA		2.3 V to 3.6 V	V _{CC} - 0.2			
		$I_{OH} = -6 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	2			
	V nort		V _{IH} = 1.7 V	2.3 V	1.7			
V_{OH}	Y port	$I_{OH} = -12 \text{ mA}$	V _{IH} = 2 V	2.7 V	2.2			V
			V _{IH} = 2 V	3 V	2.4			
		I _{OH} = -24 mA,	V _{IH} = 2 V	3 V	2			
	PARI/O	$I_{OH} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2			
		$I_{OL} = 100 \mu A$		2.3 V to 3.6 V			0.2	
		$I_{OL} = 6 \text{ mA},$	V _{IL} = 0.7 V	2.3 V			0.4	
	Y port	1 12 m A	V _{IL} = 0.7 V	2.3 V			0.7	
V_{OL}		I _{OL} = 12 mA	V _{IL} = 0.8 V	2.7 V			0.4	V
		I _{OL} = 24 mA,	V _{IL} = 0.8 V	3 V			0.55	
	PARI/O	$I_{OL} = 12 \text{ mA},$	$V_{IL} = 0.8 \ V$	3 V			0.55	
	YERR output	I _{OL} = 24 mA		3 V			0.5	
I		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
		$V_{I} = 0.7 V$		2.3 V	45			
		$V_{I} = 1.7 V$		2.3 V	-45			
I _{I(hold)}		$V_{I} = 0.8 V$		3 V	75			μΑ
		V _I = 2 V		3 V	-75			
		$V_I = 0$ to 3.6 $V^{(2)}$		3.6 V			±500	
I _{OH}	YERR output	$V_O = V_{CC}$		0 to 3.6 V			±10	μΑ
$I_{OZ}^{(3)}$		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
I_{CC}		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ
ΔI_{CC}		One input at V _{CC} - 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
C	Control inputs	V – V or CND		3.3 V		5.5		n.E
C _i	Data inputs	$V_I = V_{CC}$ or GND		3.3 V		5.5		pF
C	YERR output	V = V or GND		3.3 V		5		nE.
C _o	Data outputs	$V_0 = V_{CC}$ or GND		3.3 V		6		pF
C _{io}	PARI/O	$V_O = V_{CC}$ or GND		3.3 V		7		pF

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

For I/O ports, the parameter I_{OZ} includes the input leakage current.

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TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1 and Figure 4)

				V _{CC} = 1 ± 0.2		V _{CC} =	2.7 V	V _{CC} = 3 ± 0.3	3.3 V 3 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency				125		125		125	MHz
t _w	Pulse duration, 0	CLK↑		3		3		3		ns
		1A-12A before CLK↑	Register mode	1.7		1.9		1.45		
		1A-10A before CLK↑	Buffer mode	5.9		5.2		4.4		
		APAR before CLK↑	Register mode	1.2		1.5		1.3		
t _{su}	Setup time	APAR before CLK	Buffer mode	4.6		3.6		3.1		ns
		PARI/O before CLK↑	Both modes	2.4		2		1.7		
		11A/YERREN before CLK↑	Buffer mode	2		1.9		1.6		
		CLKEN before CLK↑	Register mode	2.5		2.6		2.2		
		1A-12A after CLK↑	Register mode	0.4		0.25		0.55		
		1A-10A after CLK↑	Buffer mode	0.25		0.25		0.25		
		APAR after CLK↑	Register mode	0.7		0.4		0.7		
	llald time	APAR after CLK	Buffer mode	0.25		0.25		0.25		
t _h	Hold time	DADI/O attar CLIV	Register mode	0.25		0.25		0.4		ns
		PARI/O after CLK↑	Buffer mode	0.25		0.25		0.5		
		11A/YERREN after CLK↑ Bu		0.25		0.25		0.4		
		CLKEN after CLK↑	Register mode	0.25		0.5		0.4		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 4)

Р	ARAMETER	FROM	TO (OUTPUT)	V _{CC} = ± 0.2		V _{CC} =	2.7 V	V _{CC} = 0.3		UNIT
		(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}				125		125		125		MHz
	Buffer mode	А	Y	1	4.4		4.2	1.1	3.8	
t _{pd}	Dath mades	CLIV	YERR	1	5.7		4.9	1.4	4.4	ns
	Both modes	CLK	PARI/O	1.2	8.6		7.9	1.7	6.6	
t _{pd} ⁽¹⁾	Both modes	CLK	PARI/O	1	6.8		5.2	1.3	4.5	ns
t _{pd}	Both modes	MODE	Y	1	5.9		5.8	1.3	4.9	ns
t _{PLH}	De sistem se e de	CLIK	Υ	1	6.1		5.5	1.2	4.8	
t _{PHL}	Register mode	CLK	Y	1	5.9		4.9	1.2	4.6	ns
	Dath mades	ŌĒ	Y	1.1	6.5		6.4	1.4	5.4	
t _{en}	Both modes	PAROE	PARI/O	1	5.6		6	1	4.8	ns
	Dath made	ŌĒ	Y	1	6.4		5.2	1.7	5	
t _{dis}	Both modes	PAROE	PARI/O	1	3.2		3.8	1.2	3.8	ns
t _{PLH}	Doth modes	ŌĒ	VEDD	1	3.6		4.2	1.9	4	
t _{PHL}	Both modes	UE	YERR	1.2	5.1		4.9	1.5	4.2	ns

⁽¹⁾ See Figure 2 and Figure 5 for the load specification.



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SIMULTANEOUS SWITCHING CHARACTERISTICS(1)

(see Figure 3 and Figure 6)

PA	RAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	Dogister mode	CLIK	V	1.8	6.5		6.1	1.8	5	20
t _{PHL}	Register mode	CLK	Ť	1.4	5.9		5.1	1.7	4.5	ns

⁽¹⁾ All outputs switching

OPERATING CHARACTERISTICS FOR BUFFER MODE

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS		TEST CONDITIONS		V _{CC} = 3.3 V ± 0.3 V	UNIT
_	Dower dissination consistence	Outputs enabled	0 0	f 40 MHz	57.5	65	, L
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 0$,	f = 10 MHz	15	17.5	pF

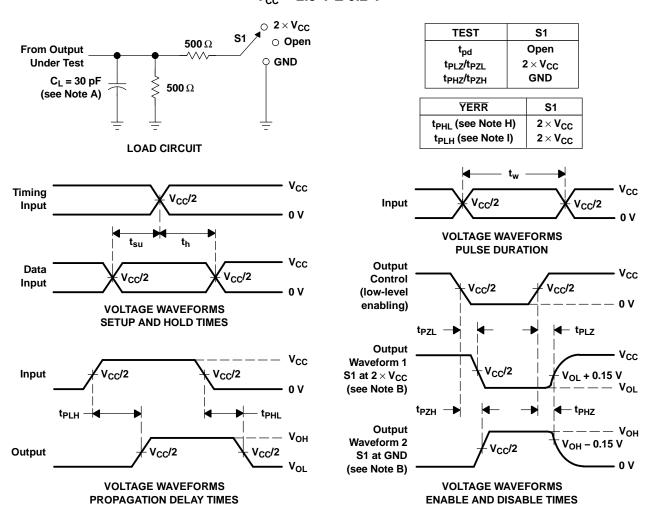
OPERATING CHARACTERISTICS FOR REGISTER MODE

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS		V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
	Dower dissination consistence	Outputs enabled	C 0	f = 10 MHz	57	87.5	~F
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 0$,	I = 10 WINZ	16.5	34	pF



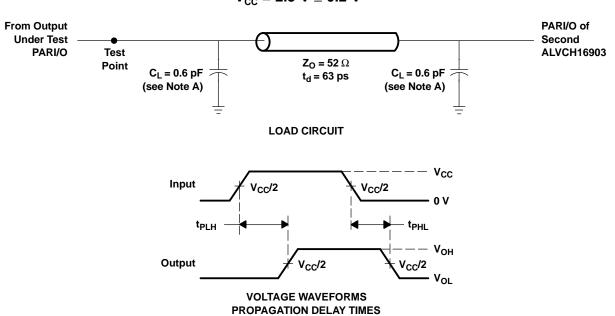
PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



- NOTES: A. C₁ includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.
 - H. t_{PHL} is measured at $V_{CC}/2$.
 - I. t_{PLH} is measured at V_{OL} + 0.15 V.

Figure 1. Load Circuit and Voltage Waveforms

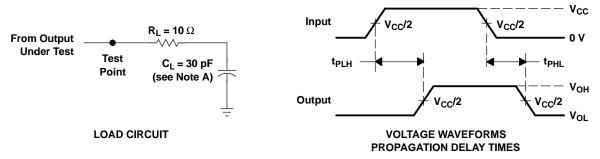
PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- C. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms



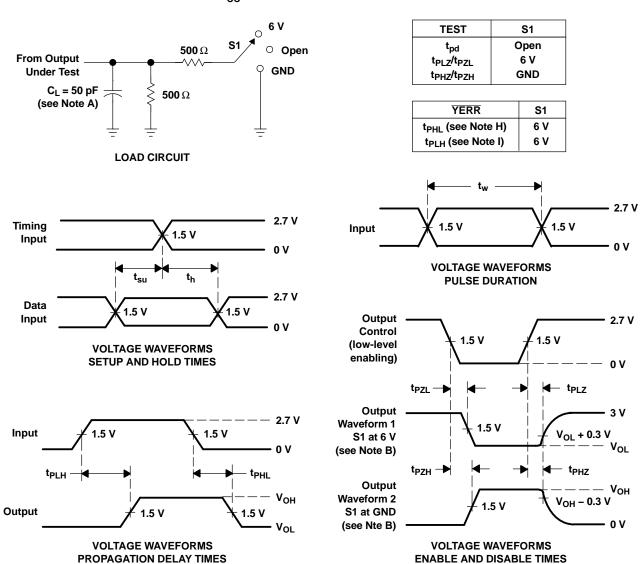
NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns.

Figure 3. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V

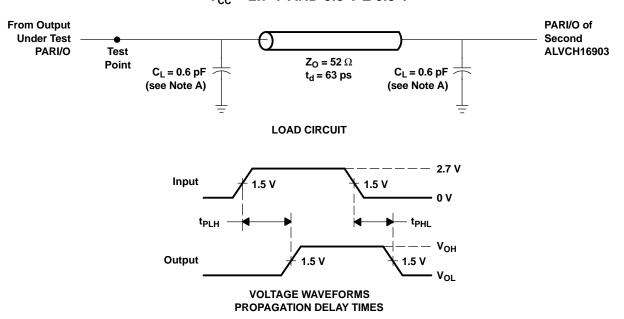


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. t_{PHL} is measured at 1.5 V.
- I. t_{PLH} is measured at V_{OL} + 0.3 V.

Figure 4. Load Circuit and Voltage Waveforms

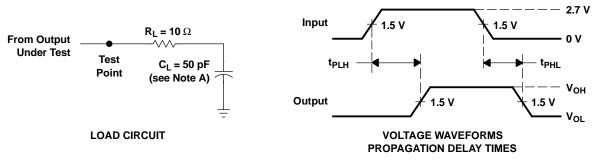
PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- C. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 5. Load Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.

Figure 6. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74ALVCH16903DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16903	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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